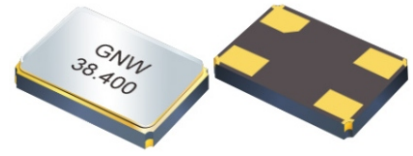


1.6×1.2 SMD Crystal



APPLICATIONS

- Bluetooth / Wireless LAN
- Wearable Devices
- LTE / SAS

FEATURE

- Rugged AT-cut crystal construction
- Miniature 1.6×1.2mm ceramic package
- Anti-EMI design

- Tight Tolerance and Stability
- Reflow Soldering/Emboss Taping



Electrical Specifications 电气参数

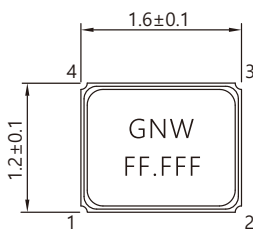
| 项目 | Item/Type | Electrical Specifications |
|--------|------------------------------|--|
| 频率范围 | Frequency Range | 24MHz to 60MHz |
| 调整频差 | Frequency Tolerance(at 25°C) | ±10ppm to ±30ppm |
| 温度频差 | Frequency Drift | ±10ppm to ±30ppm |
| 工作温度范围 | Operating Temperature Range | -20°C ~ +70°C, -40°C ~ +85°C or -40°C ~ +105°C |
| 储存温度范围 | Storage Temperature Range | -55°C ~ +125°C |
| 老化 | Aging (25°C) | ±3ppm/year max. |
| 静电容 | Shunt Capacitance (C0) | 3pF max. |
| 激励功率 | Drive Level | 10μW Typical |
| 绝缘阻抗 | Insulation Resistance (Rs) | 500 Megaohms min. at D.C 100v |
| 负载电容 | Load Capacitance (CL) | 6,8,12pF or specify |

Equivalent Series Resistance and Mode of Operation 等效阻抗和振荡模式

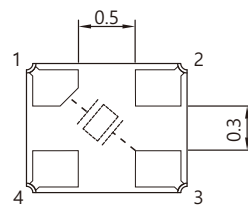
| Frequency Range 频率范围 | ESR (Ω) 等效阻抗 | Mode 振荡模式 |
|----------------------|----------------|-------------|
| 24~32MHz | 150Ω max. | Fundamental |
| 32~36MHz | 100Ω max. | Fundamental |
| 36~60MHz | 80Ω max. | Fundamental |

Mechanical Dimensions 外型尺寸

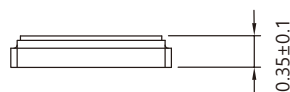
Units:mm



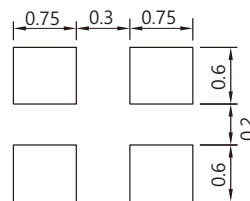
Top View



Bottom View



Side View



Land Pattern

Pin Connection

| | |
|-------|---------|
| #1,#3 | Crystal |
| #2,#4 | GND |